

**WE CLAIM:**

1. A die pad of a leadframe, the die pad for receiving a die, the die pad comprising:

5 a plurality of slots penetrating the die pad and having a restrictive region defined by the slots, whereby a solder paste for connecting the die with the die pad is restricted within the restrictive region.

2. The die pad as claimed in Claim 1, wherein the area of the restrictive region is equal to the area of the die.

3. The die pad as claimed in Claim 1, wherein the slots are located at at least one side of the restrictive region.

4. The die pad as claimed in Claim 1, wherein the slots are located at at least one corner of the restrictive region.

5. A leadframe comprising a plurality of die pads and a plurality of pins, wherein the die pad is used for receiving a die, characterized in that each die pad comprises:

20 a plurality of slots penetrating the die pad and having a restrictive region defined by the slots, whereby a solder paste for connecting the die with the die pad is restricted within the restrictive region.